Chip on Board

HW27U-HF

A COB wire bonder for flexible performance and for wider-area bonding

- High speed bonding: 0.15 s/wire
- High-reliability with US monitor [optional] and gray-scale recognition
- Easy-to-operate color display
- Great variety of wire bonding techniques
  - Chip to chip, Lead to lead, Staggered wiring
  - Support for small balls
  - Bonding data is changeable for each wire

<table>
<thead>
<tr>
<th>Model name</th>
<th>HW27U-HF</th>
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<tbody>
<tr>
<td>Model No.</td>
<td>KXF-3E2H</td>
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<tr>
<td>Cycle time</td>
<td>non-loop control: 0.15 s/wire (Loop length 2 mm) loop control: 0.17 s/wire (Loop length 2 mm)</td>
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<tr>
<td>Bonding accuracy</td>
<td>±5 µm (In 6x lens and gray-scale recognition)</td>
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<tr>
<td>Substrate dimensions</td>
<td>L 50 mm × W 20 mm to L 310 mm × W 100 mm</td>
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<tr>
<td>Bonding area</td>
<td>End-face clamp: Max. L 115 mm × W 95 mm Mask type: Max. L 115 mm × W 83 mm</td>
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<tr>
<td>Bonding method</td>
<td>Gold bonding method using both ultrasonic and thermocompression bonding</td>
</tr>
<tr>
<td>Electric source</td>
<td>Single phase AC 200 V ±10 V, 2.5 kVA</td>
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<tr>
<td>Pneumatic source</td>
<td>440 kPa, 50 L/min [Standard]</td>
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<tr>
<td>Dimensions</td>
<td>W 1510 mm × D 880 mm × H 1510 mm</td>
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<tr>
<td>Mass</td>
<td>550 kg</td>
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</table>

*Values such as cycle time and bonding accuracy may vary depending on operating conditions.*

*Please refer to the specifications on details.*
Wire bonding for a wide variety of boards

- Printer head, Image sensor, etc.
  - L=500mm
  - L=1000mm
  - L=1500mm

- Communication, Audio Visual, Car electronics, device, etc.
  - W=100mm
  - W=120mm
  - W=160mm

- Wafer bump, Chip bump
  - D=150mm
  - D=100mm
  - Piece chip carrier transport

Support for the great-step-height bonding of electronic components

- Tilt-less high-quality bonding in spite of great step height
- High-precision bonding through the recognition of great step height

Z-axis elevating module

Safety Cautions

To ensure safety when using this equipment, all work should be performed according to that as stated in the separate Operating Instructions. Read your operating instructions manually thoroughly.

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All data as of May 1, 2003.

*Changes in specifications and appearance may be made without notice for product improvement.